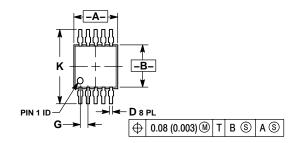
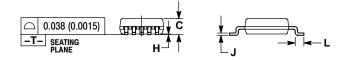




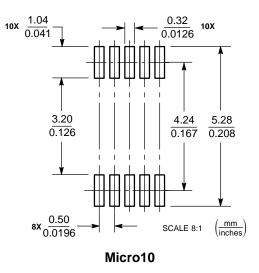
SCALE 2:1



Micro10 CASE 846B-03 ISSUE D



SOLDERING FOOTPRINT



DATE 07 DEC 2004

- NOTES: 1. DIMENSIONING AND TOLERANCING PER
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: MILLIMETER. DIMENSION 'A' DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURDED GUIL, NOT EVOLED AUT (ACC) 2. 3.
- MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
 10 DIMENSION "B" DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION. SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
 10 ABSOLETE. NEW STANDARD 846B-02

	MILLIMETERS INCHES		HES	
DIM	MIN	MAX	MIN	MAX
Α	2.90	3.10	0.114	0.122
В	2.90	3.10	0.114	0.122
С	0.95	1.10	0.037	0.043
D	0.20	0.30	0.008	0.012
G	0.50 BSC		0.020 BSC	
Н	0.05	0.15	0.002	0.006
J	0.10	0.21	0.004	0.008
Κ	4.75	5.05	0.187	0.199
L	0.40	0.70	0.016	0.028

GENERIC **MARKING DIAGRAM***

	<u>_0.0.0.00</u> _
	XXXX AYW O THTTTTT
xxxx A	= Device Code = Assembly Location
Y	= Year
W	= Work Week
•	= Pb–Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

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STATUS:	ON SEMICONDUCTOR STANDARD		
NEW STANDARD:			
DESCRIPTION:	Micro10		PAGE 1 OF 2





ISSUE	REVISION	DATE		
0	RELEASED FOR PRODUCTION. REQ BY J. HOSKINS.	09 NOV 2000		
А	DIM "D" WAS 0.25–0.4MM/0.10–0.016IN. ADDED NOTE 5. USED ON: WAS 10 LEAD TSSOP, PITCH 0.65 REQ BY J. HOSKINS.	13 NOV 2000		
В	CHANGED "USED ON" WAS: 10 LEAD TSSOP, PITCH 0.50MM. REQ BY A. HAMID.	11 JUL 2001		
С	CHANGED "D" DIMENSION MAX FROM 0.35 TO 0.30MM AND 0.014 TO 0.012IN. REQ BY D. TRUHITTE.	31 JUL 2003		
D	ADDED FOOTPRINT INFORMATION. REQ. BY K. OPPEN.	07 DEC 2004		

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